GSX18N60E

MOSFET

Metal Oxide Semiconductor Field Effect Transistor

Super Junction MOSFET

600V Super Junction Power Transistor

GSX18N60E

Data Sheet

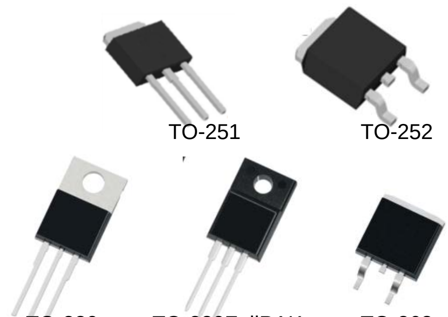
Ver 1.1

2019-3-20

600V 18A Power MOSFET

■Description

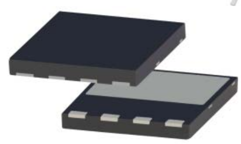
GroupSemiconductor(GS) has series Multi-EPI Super-Junction power MOSFET platforms for voltage up 500V to 1000 volts, both with design service and manufacturing capability, including cell, termination design and simulation.
The GS 600V 18A Power MOSFET is a Low voltage N channel Multi-EPI Super-Junction power MOSFET sample with advanced technology to have better characteristics, such as fast switching time, low Ciss and Crss, low on resistance and excellent avalanche characteristics, making it especially suitable for applications which require superior power density and outstanding efficiency.



■ Features

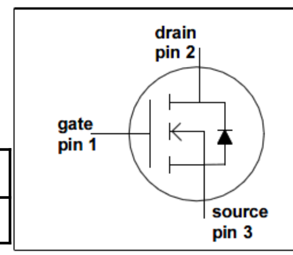
RDS(ON)=0.25Ω @VGS = 10V
VDS = 600V
ID (@ VGS=10V) = 9A

DFN8*8



■ PKG

GSA18N60E	GSP18N60E	GSB18N60E	GSD18N60E	GSS18N60E	GSL18N60E
TO-220Fullpak	TO-220	TO-263	TO-252	TO-251	DFN8*8



■Absolute Maximum Ratings (TC = 25° C, unless otherwise specified)

Symbol	Parameter	GSP18N60E	GSA18N60E	Unit
V_{DSS}	Drain-Source Voltage	600		V
I_D	Drain Current -Continuous (TC = 25°C) -Continuous (TC = 100°C)	18* 13*		A
I_{DM}	Drain Current - Pulsed (Note 1)	55		A
V_{GSS}	Gate-Source voltage	±30		V
E_{AS}	Single Pulsed Avalanche Energy (Note 2)	320		mJ
I_{AR}	Avalanche Current (Note 1)	3		A
E_{AR}	Repetitive Avalanche Energy (Note 1)	2		mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	15		V/ns
dVds/dt	Drain Source voltage slope (Vds=480V)	50		V/ns
P_D	Power Dissipation (TC = 25°C)	151	35	W
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to +150		°C
T_L	Max. Lead Temperature for Soldering Purpose, 1/8″ from Case for 5 Seconds	300		°C

■Thermal Characteristics

Symbol	Parameter	GSA18N60E	GSP18N60E	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	1.2	1.2	℃/W
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink Typ.	0.5	0.5	℃/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	62	62	℃/W

Symbol	Parameter	Value (TO220)	Unit
$R_{\theta JA}$ (6)	Maximum Junction-to-Ambient	82	℃/W
$R_{\theta CS}$ (6)	Maximum Case-to-sink	0.6	℃/W
$R_{\theta JC}$ (7),(8)	Maximum Junction-to-Case θ	4.1	□℃/W

1. The power dissipation PD is based on TJ(MAX)=150° C in a TO251 package, using junction-to-case thermal resistance.
2. Repetitive rating, pulse width limited by junction temperature TJ(MAX)=150° C.
3. L=1mH, Starting TJ=25° C.
4. L = 10mH, starting TJ = 25° C.
5. L=60mH, starting TJ = 25° C.
6. The tests are performed with the device with T A =25° C.
7. The R □ JA is the sum of the thermal impedance from junction to case R □ JC and case to ambient.
8. These curves are based on the junction-to-case thermal impedance, assuming a maximum junction temperature of TJ(MAX)=150° C.

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■ Electrical Characteristics (TJ=25° C unless otherwise specified)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS} = 0V, I_D = 250µA, T_J = 25℃	600	--	--	V
		V_{GS} = 0V, I_D = 250µA, T_J = 150℃	--	650	--	V
$\Delta BV_{DSS}/\Delta T_J$	Breakdown Voltage Temperature Coefficient	I_D = 250µA, Referenced to 25℃	--	0.6	--	V/℃
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS} = 600V, V_{GS} = 0V -T_J = 150℃	--	-- 10	1 -	µA µA
I_{GSSF}	Gate-Body Leakage Current, Forward	V_{GS} = 30V, V_{DS} = 0V	--	--	100	nA
I_{GSSR}	Gate-Body Leakage Current, Reverse	V_{GS} = -30V, V_{DS} = 0V	--	--	-100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS} = V_{GS}, I_D = 250µA	2.5	--	4.5	V
$R_{DS(on)}$	Static Drain-Source On-Resistance	V_{GS} = 10V, I_D = 9A	--	0.22	0.25	Ω
g_{FS}	Forward Transconductance	V_{DS} = 40V, I_D = 9A	--	16	--	S
Dynamic Characteristics						
C_{iss}	Input Capacitance	V_{DS} = 25V, V_{GS} = 0V, f = 1.0MHz	--	1230	-	pF
C_{oss}	Output Capacitance		--	30	-	pF
C_{rss}	Reverse Transfer Capacitance		--	2.6	--	pF
Switching Characteristics						
$t_{d(on)}$	Turn-On Delay Time	V_{DD} = 400V, I_D =9A R_G = 20Ω (Note 4)	--	20	--	ns
t_r	Turn-On Rise Time		--	17	--	ns
$t_{d(off)}$	Turn-Off Delay Time		--	170	--	ns
t_f	Turn-Off Fall Time		--	13	--	ns
Q_g	Total Gate Charge	V_{DS} = 400V, I_D = 9A V_{GS} = 10V (Note 4)	--	42	--	nC
Q_{gs}	Gate-Source Charge		--	6	--	nC
Q_{gd}	Gate-Drain Charge		--	29	--	nC
Drain-Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Drain-Source Diode Forward Current		--	--	18	A
I_{SM}	Maximum Pulsed Drain-Source Diode Forward Current		--	--	42	A
V_{SD}	Drain-Source Diode Forward Voltage	V_{GS} = 0V, I_S = 9A	--	0.9	1.5	V
t_{rr}	Reverse Recovery Time	V_{GS} = 0V, I_S = 9A dI_F/dt =100A/µs	--	380	--	ns
Q_{rr}	Reverse Recovery Charge		--	4.5	--	µC

NOTES:

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. L=60mH, I_{AS}=4A, VDD=150V, Starting TJ=25 ℃
3. I_{SD}≤4.5A, di/dt ≤ 200A/us, V_{DD} ≤ BV_{DSS}, Starting TJ = 25 ℃
4. Pulse Test: Pulse width ≤ 300us, Duty Cycle ≤ 2%
5. Essentially Independent of Operating Temperature Typical Characteristics

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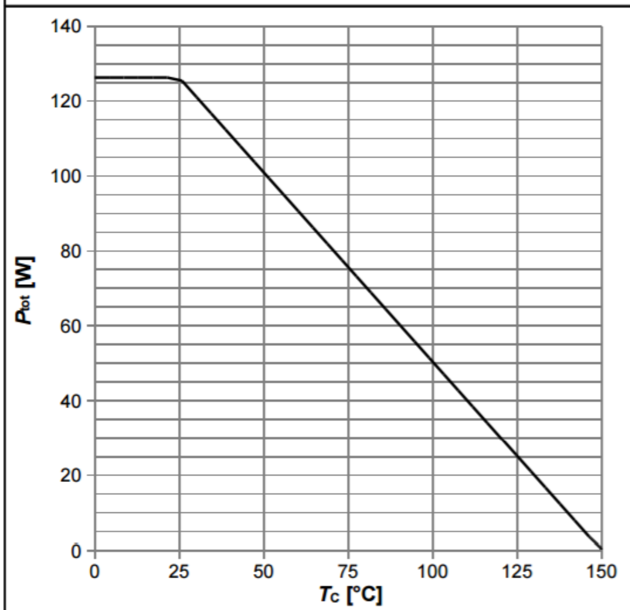
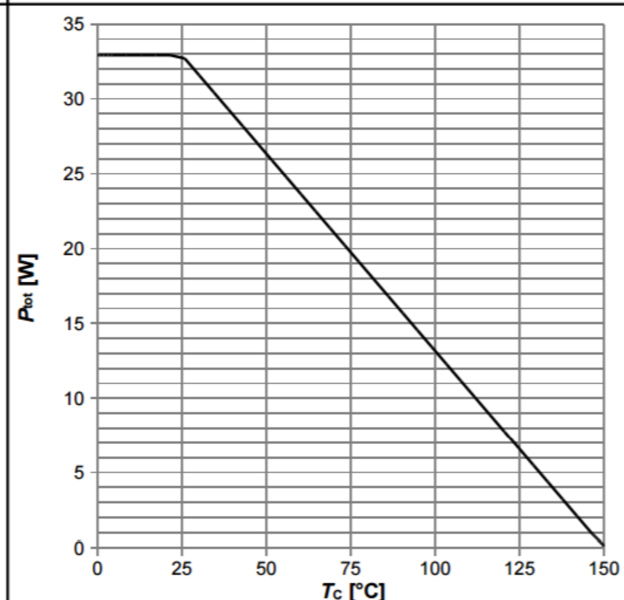
Typical Performance Characteristics

Diagram 1: Power dissipation (Non FullPAK)



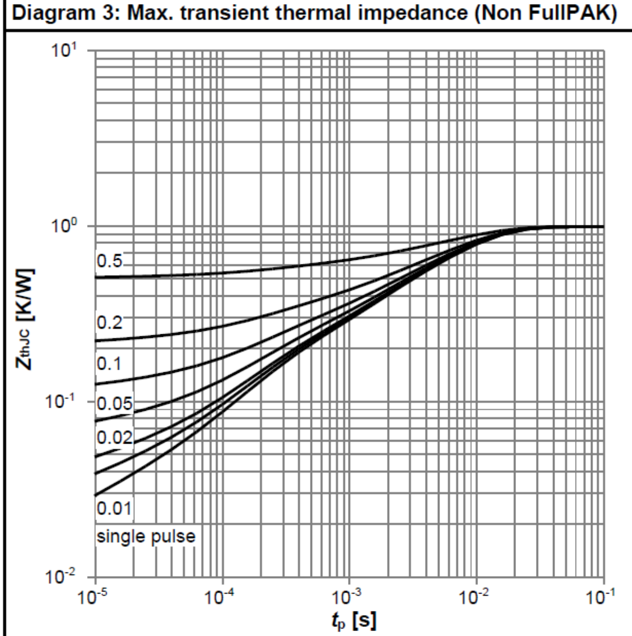
P_{tot}=f(T_C)

Diagram 2: Power dissipation (FullPAK)



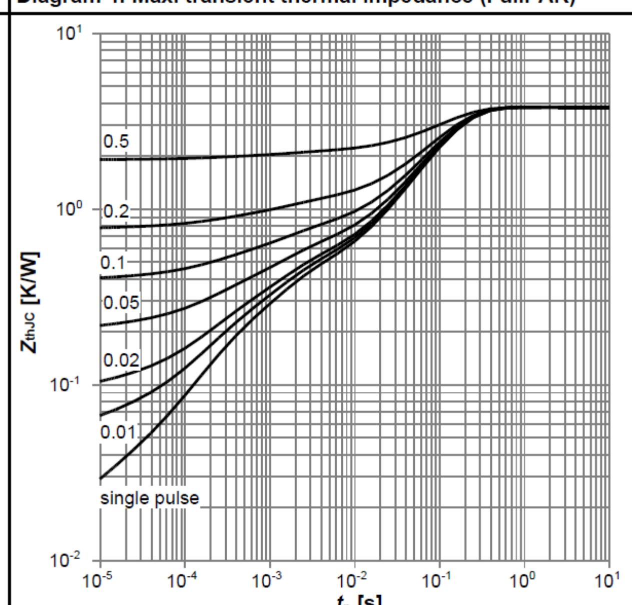
P_{tot}=f(T_C)

Diagram 3: Max. transient thermal impedance (Non FullPAK)



Z_{thJC} =f(t_P); parameter: $D=t_p/T$

Diagram 4: Max. transient thermal impedance (FullPAK)



Z_{thJC} =f(t_P); parameter: $D=t_p/T$

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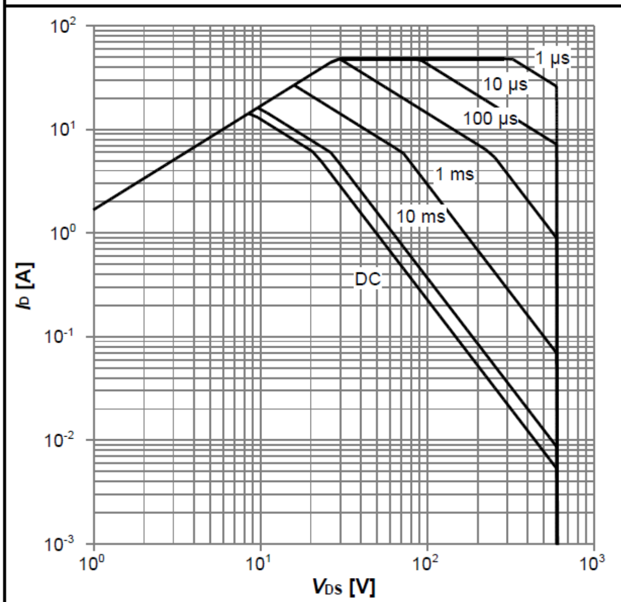
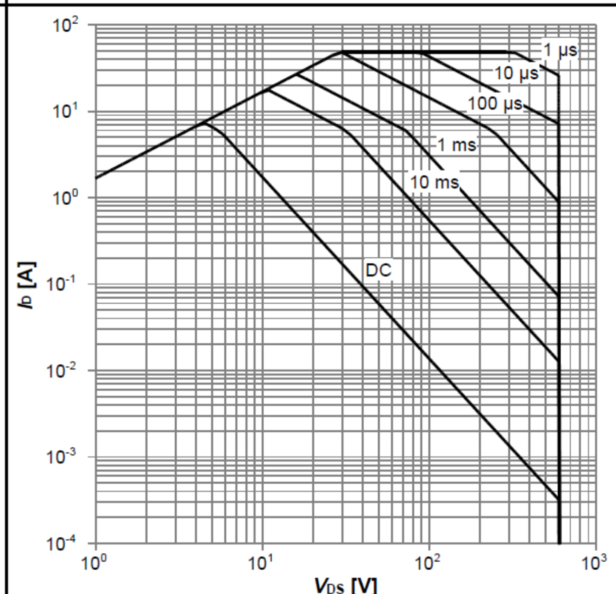
Typical Performance Characteristics

Diagram 5: Safe operating area (Non FullPAK)



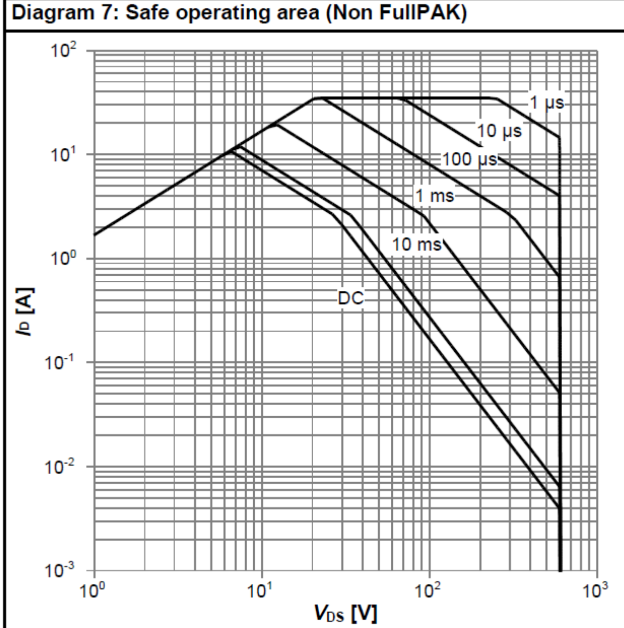
I_D=f(V_{DS}); T_C=25 °C; D=0; parameter: t_p

Diagram 6: Safe operating area (FullPAK)



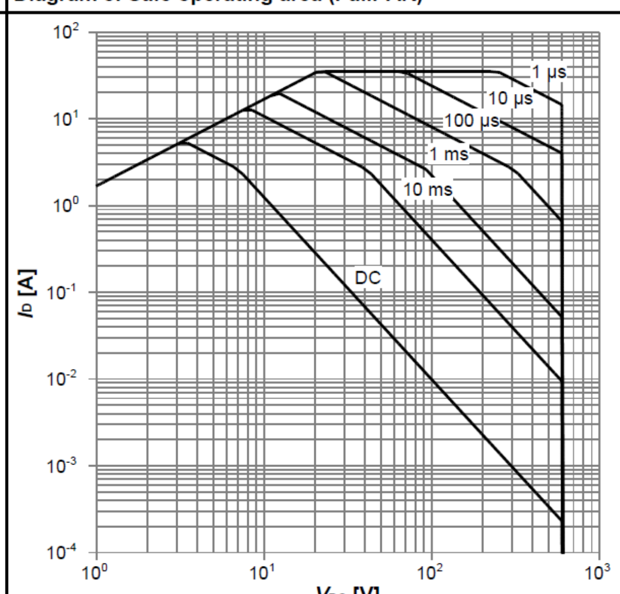
I_D=f(V_{DS}); T_C=25 °C; D=0; parameter: t_p

Diagram 7: Safe operating area (Non FullPAK)



I_D=f(V_{DS}); T_C=80 °C; D=0; parameter: t_p

Diagram 8: Safe operating area (FullPAK)



I_D=f(V_{DS}); T_C=80 °C; D=0; parameter: t_p

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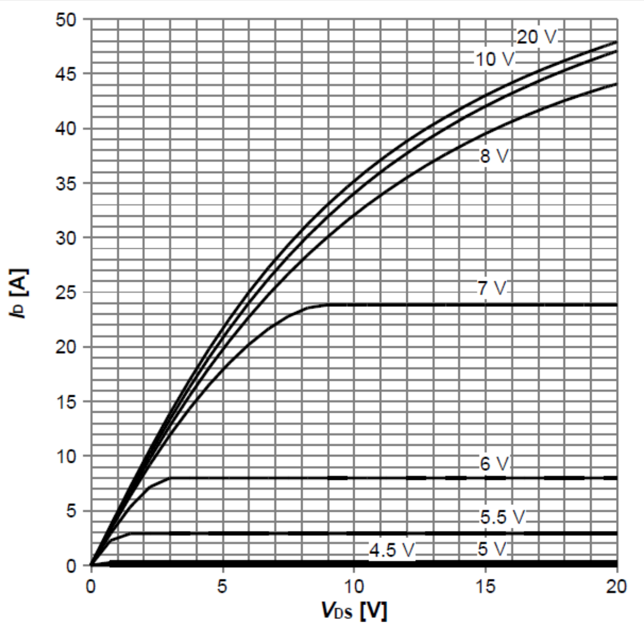
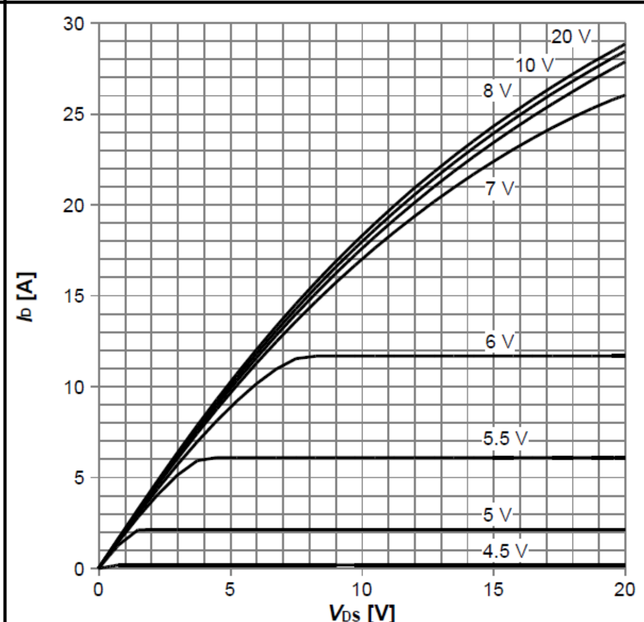
Typical Performance Characteristics

Diagram 9: Typ. output characteristics



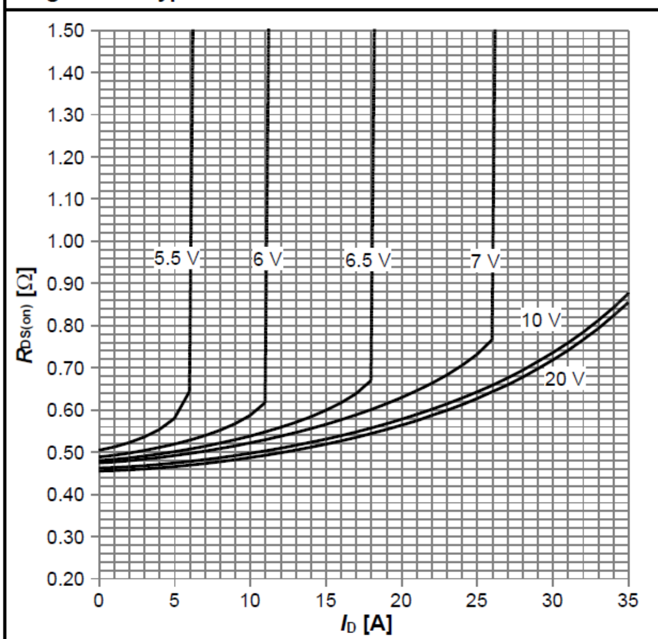
I_D=f(V_{DS}); T_j=25 °C; parameter: V_{GS}

Diagram 10: Typ. output characteristics



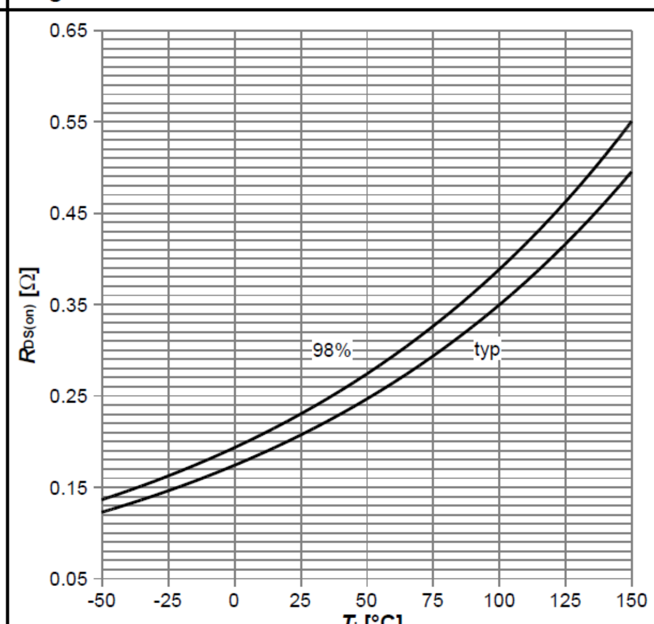
I_D=f(V_{DS}); T_j=125 °C; parameter: V_{GS}

Diagram 11: Typ. drain-source on-state resistance



$R_{DS(on)}$=f(I_D); T_j=125 °C; parameter: V_{GS}

Diagram 12: Drain-source on-state resistance



$R_{DS(on)}$=f(T_j); I_D=6.4 A; V_{GS}=10 V

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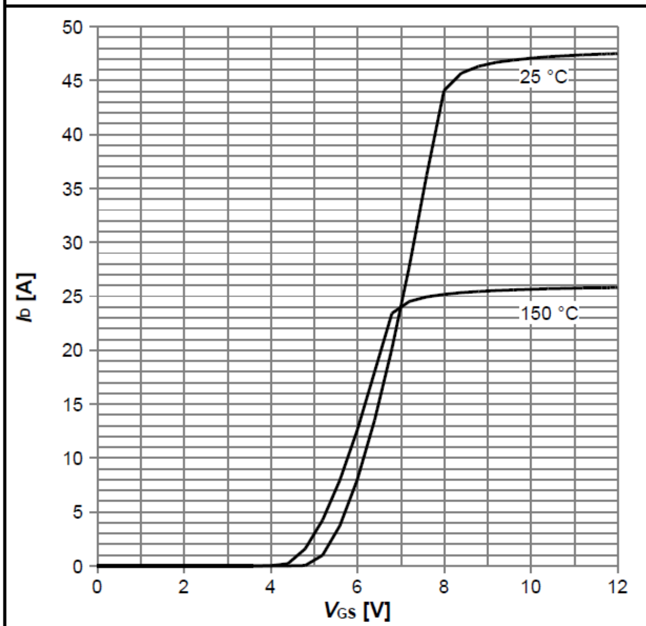
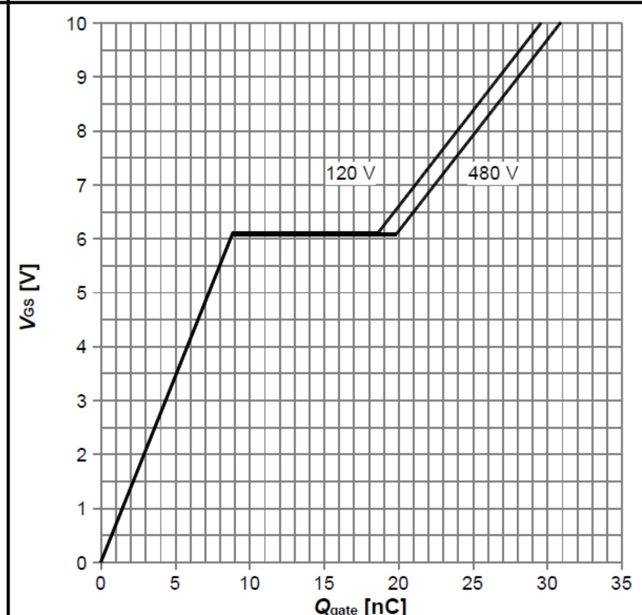
Typical Performance Characteristics

Diagram 13: Typ. transfer characteristics



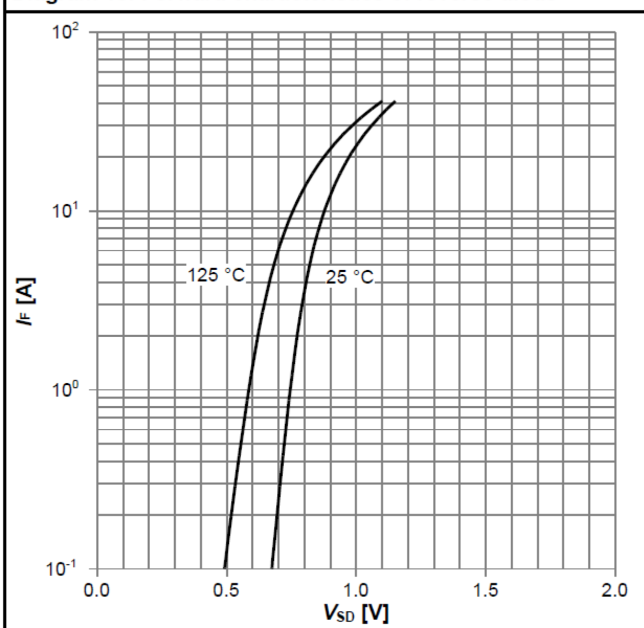
I_D=f(V_{GS}); V_{DS}=20V; parameter: T_j

Diagram 14: Typ. gate charge



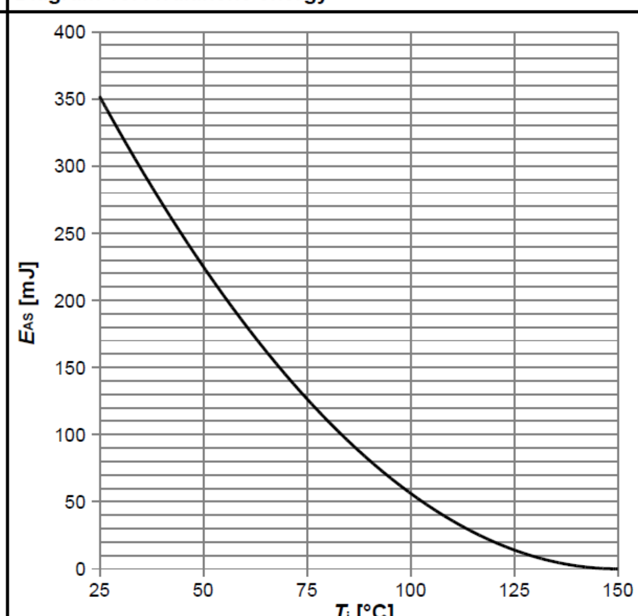
V_{GS}=f(Q_{gate}); I_D=8.0 A pulsed; parameter: V_{DD}

Diagram 15: Forward characteristics of reverse diode



I_F=f(V_{SD}); parameter: T_j

Diagram 16: Avalanche energy



E_{AS}=f(T_j); I_D=2.9 A; V_{DD}=50 V

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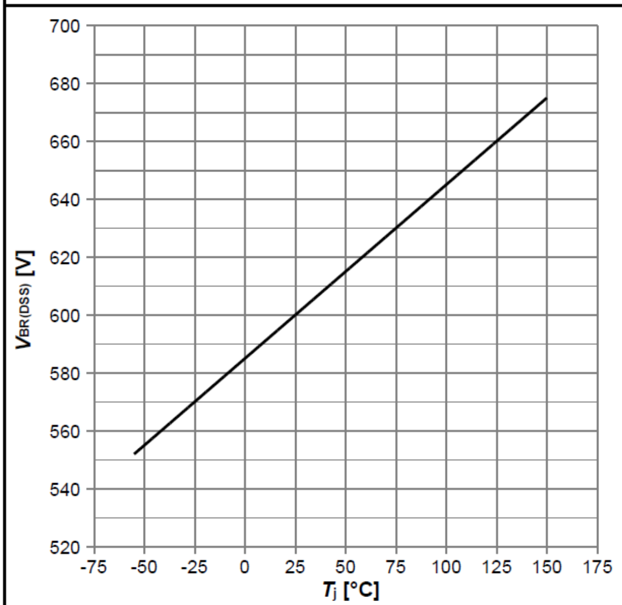
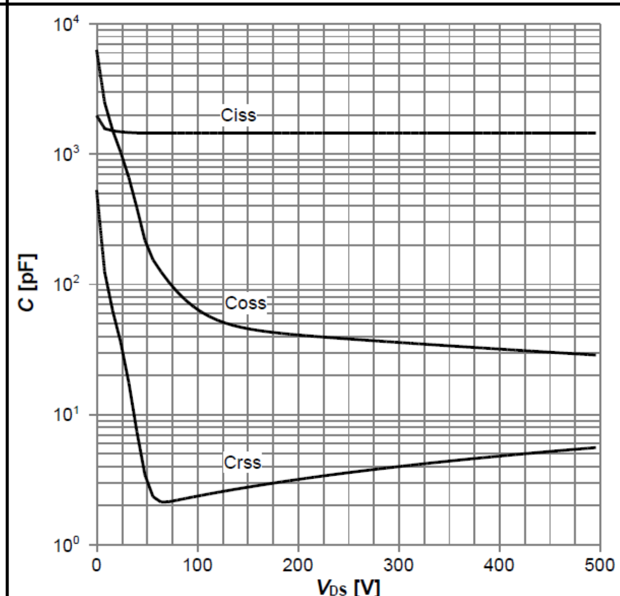
Typical Performance Characteristics

Diagram 17: Drain-source breakdown voltage



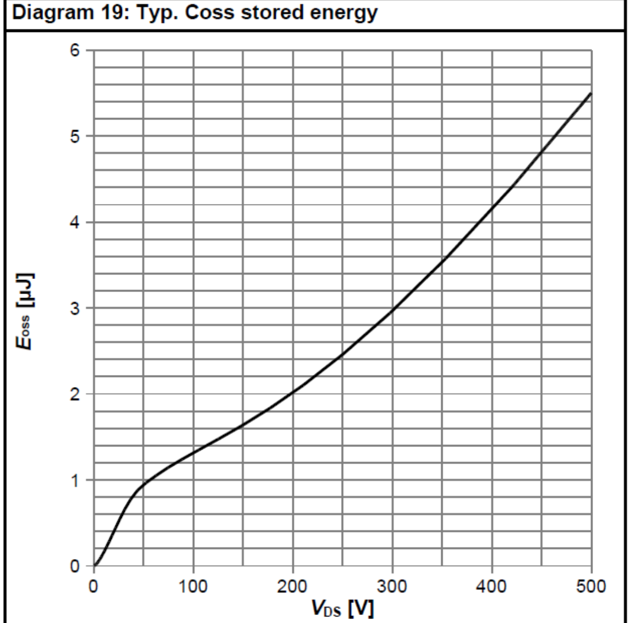
$V_{BR(DSS)}$=f(T_j); I_D=1 mA

Diagram 18: Typ. capacitances



C=f(V_{DS}); V_{GS}=0 V; f=1 MHz

Diagram 19: Typ. Coss stored energy



E_{oss}=f(V_{DS})

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Table 20 Switching times test circuit and waveform for inductive load

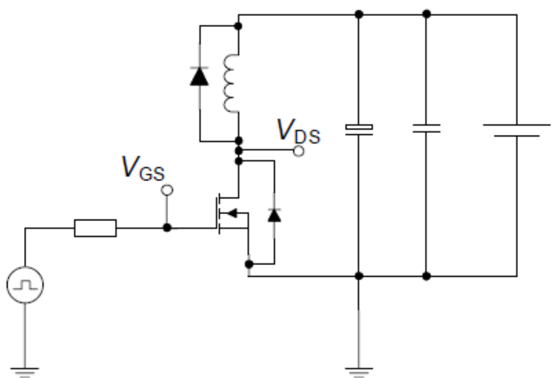
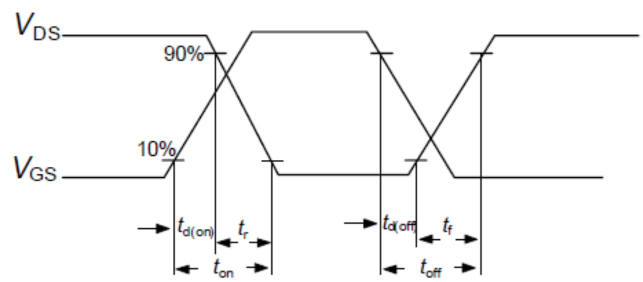
Switching times test circuit for inductive load	Switching time waveform
	

Table 21 Unclamped inductive load test circuit and waveform

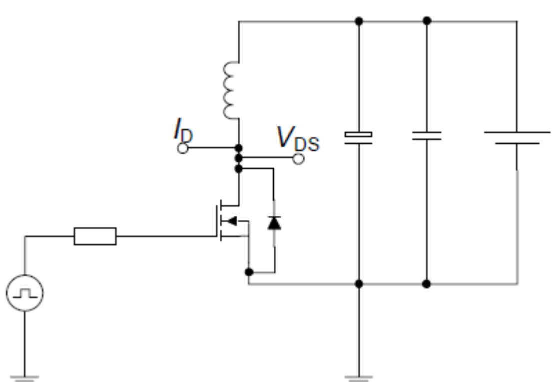
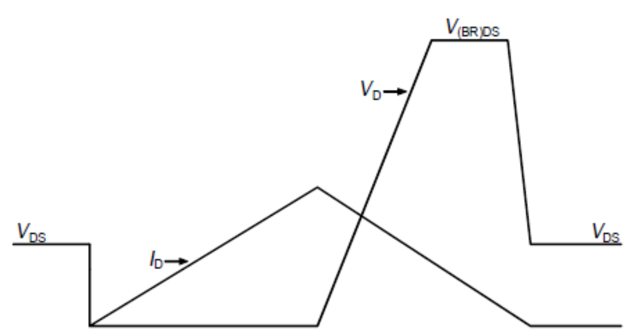
Unclamped inductive load test circuit	Unclamped inductive waveform
	

Table 22 Test circuit and waveform for diode characteristics

Test circuit for diode characteristics	Diode recovery waveform